

Notice of References Cited	Application/Control No. 10/811,408	Applicant(s)/Patent Under Reexamination STARK, DAVID H.	
	Examiner Jason L. Lazorcik	Art Unit 1731	Page 1 of 1

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	L	US-			
	M	US-			

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Bayrashev, A., Ziaie, B., "Silicon wafer bonding through RF dielectric heating", Sensors and Actuators A: Physical, Volume 103, Issues 1-2, 15 January 2003, Pages 16-22. Relevant text see page 21, column 2, paragraph 2
	V	"Pyrex", (Http://en.wikipedia.org/wiki/Pyrex) Accessed October 11, 2006
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.